

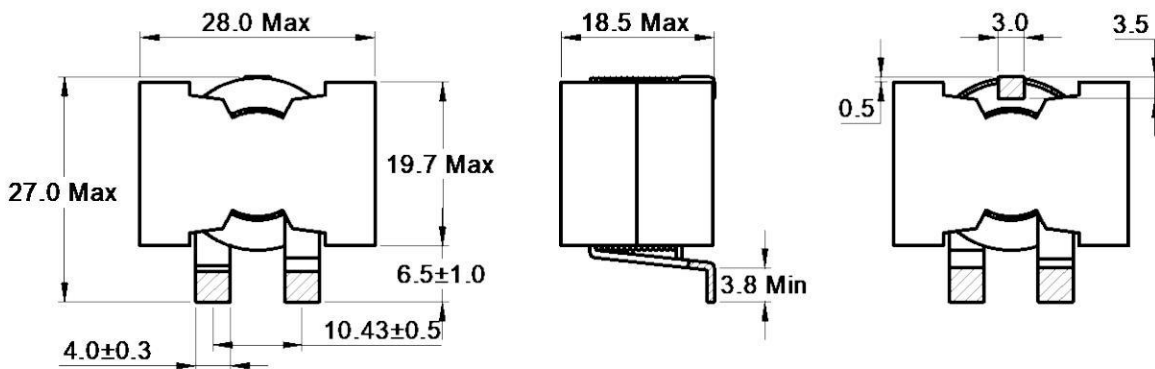


## Outline: 产品概要

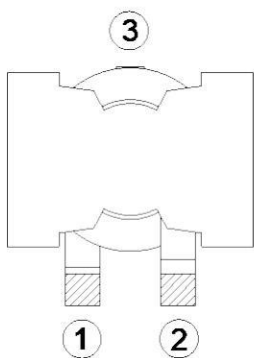
- Assemblage design, sturdy structure.  
组立式设计，结构坚固。
- High inductance, high current, low magnetic loss, low ESR, small parasitic capacitance.  
高电感值，大电流，低磁损，低阻抗，寄生电容小。
- Flat wire winding, achieve a low D.C. Resistance.  
扁平线绕组，实现极低的直流电阻。
- Low power loss, suitable for applications of wide temperature and frequency range.  
低损耗设计，适合宽频宽温环境应用。
- Operating temperature :  $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$   
(Including coil's temperature rise)  
工作温度： $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$  (包含线圈发热)



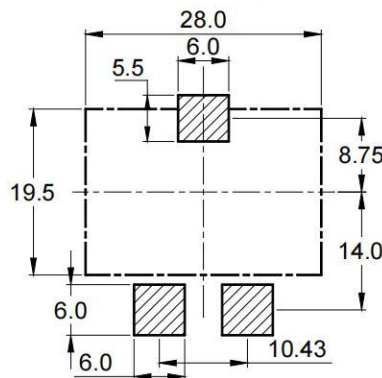
## 1 Appearance and Dimensions (mm) 外形尺寸(mm)



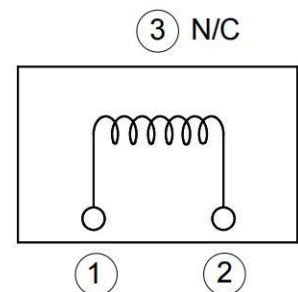
## 2 Marking 印字标识



## 3 Reference Land Pattern (mm) 参考基板尺寸 (mm)



## 4 Schematic 原理图



※ Date code will be changed by manufacture date.  
生产日期代码将根据生产日期变动。



## 5 Electrical Characteristics

### 电气特性

Part No. 型号	Inductance ( $\mu$ H) 电感值 ※1 $\pm 20\%$	D.C.R. (m $\Omega$ ) 直流电阻		Saturation current (A) 饱和电流 ※2 Typical	Temperature rise current (A) 温升电流 ※3 Typical
		Typical	Max.		
CSCF2918H-3R3MC	3.30	2.15	2.58	94.0	30.0
CSCF2918H-4R7MC	4.70	2.15	2.58	65.0	30.0
CSCF2918H-6R8MC	6.80	2.15	2.58	48.0	30.0
CSCF2918H-100MC	10.0	2.15	2.58	33.0	30.0
CSCF2918H-150MC	15.0	2.15	2.58	24.0	30.0
CSCF2918H-220MC	22.0	2.15	2.58	15.0	30.0
CSCF2918H-330MC	33.0	2.15	2.58	10.5	30.0

■ All data is tested based on 25°C ambient temperature.  
所有数据基于环境温度 25°C条件下测试。

※1 Inductance measure condition at 100kHz, 0.1V.  
电感测试条件为 100kHz, 0.1V。

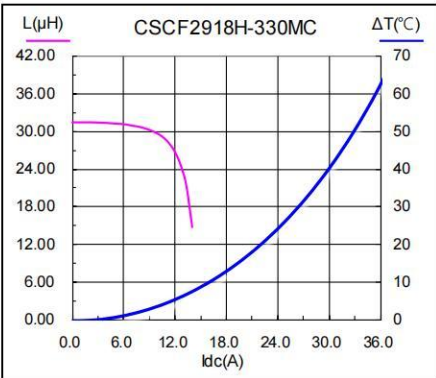
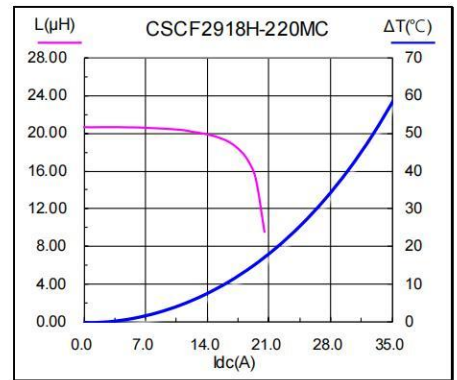
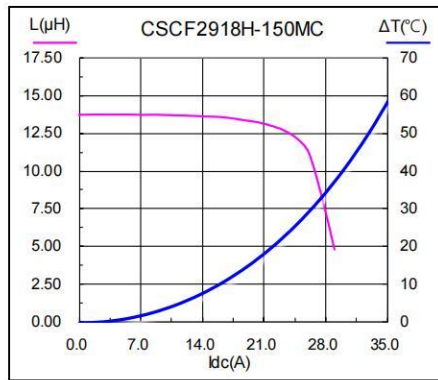
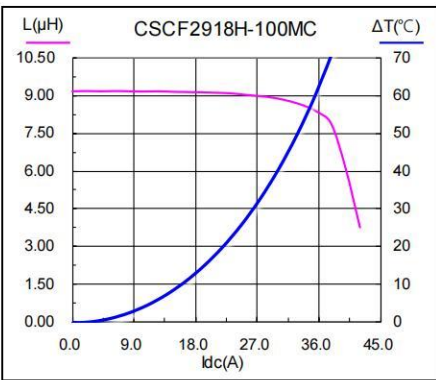
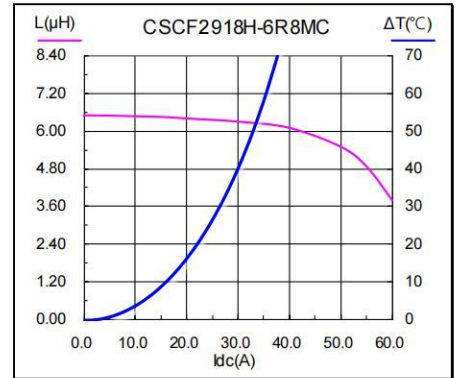
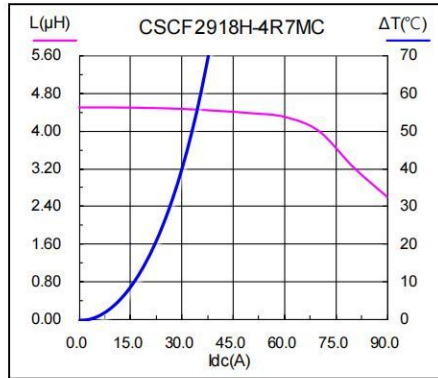
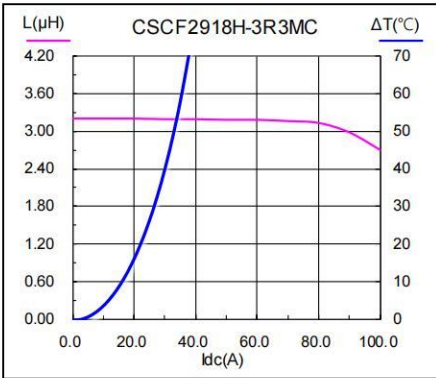
※2 Saturation current: the actual value of DC current when the inductance decrease 30% of its initial value.  
饱和电流: 电感值下降其初始值的 30%时所加载的实际直流电流值。

※3 Temperature rise current: the actual value of DC current when the temperature rise is  $\Delta T40^{\circ}\text{C}$  ( $T_a=25^{\circ}\text{C}$ ).  
温升电流: 使产品温度上升到  $\Delta T40^{\circ}\text{C}$ 时所加载的实际直流电流值( $T_a=25^{\circ}\text{C}$ )。

※ Special remind: Circuit design, component placement, PCB size and thickness, cooling system and etc. all will affect the product temperature. Please verify the product temperature in the final application.  
特别提醒: 线路设计, 组件布局, 印刷线路板(PCB)尺寸及厚度, 散热系统等均会影响产品温度。请务必在最终应用时, 验证产品发热状况。



## 6 Saturation Current vs Temperature Rise Current Curve 饱和电流 vs 温升电流曲线





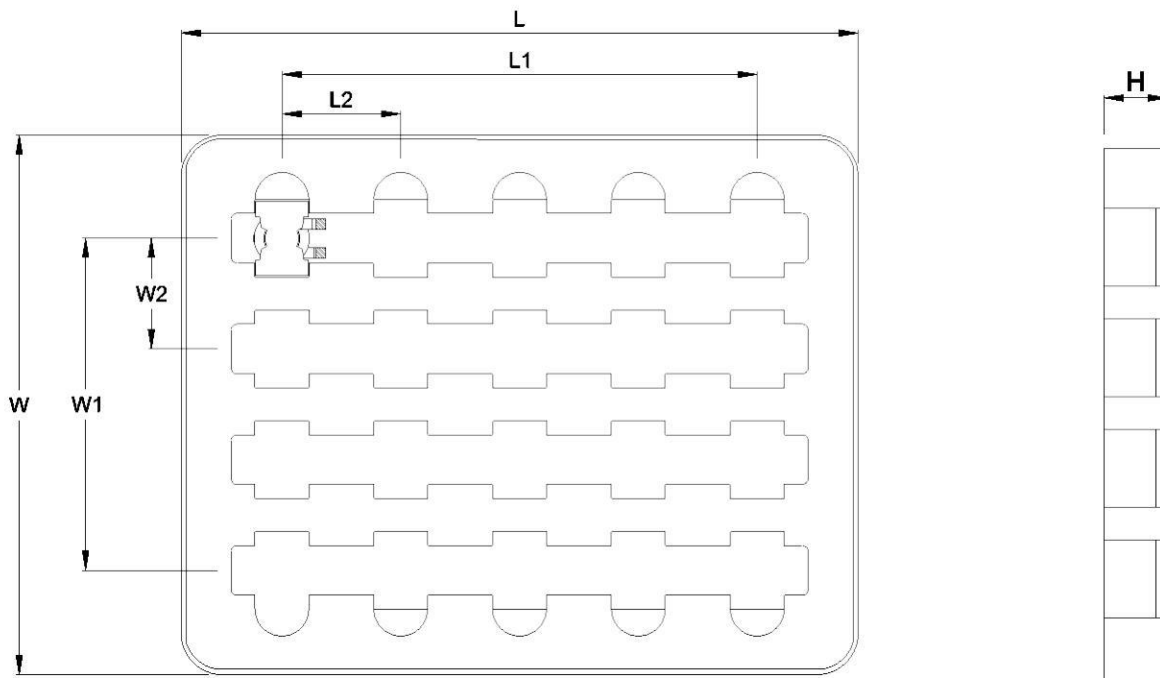


## 7 Packing Specification

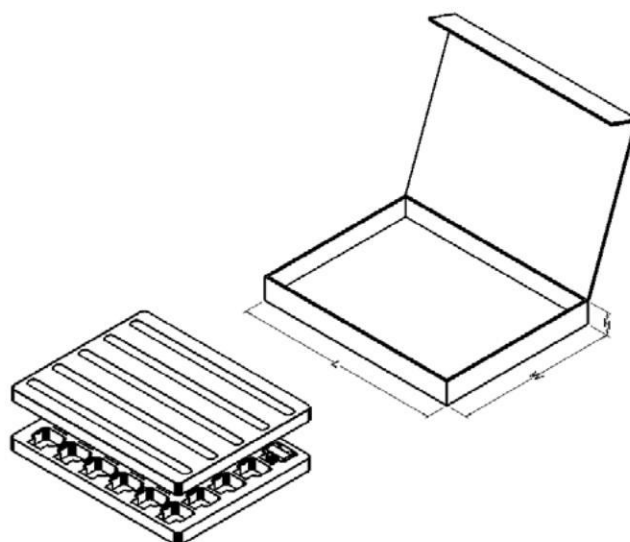
### 包装规格

#### 7.1 Plastic Tray Dimensions (mm)

吸塑盘尺寸(mm)



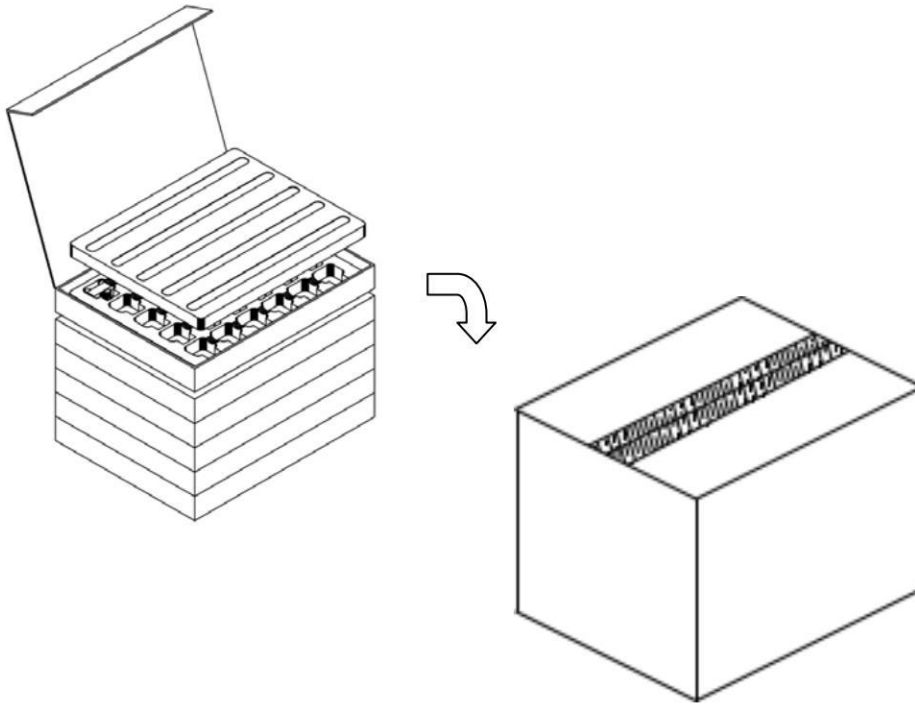
L typ	L1 typ	L2 typ	W typ	W1 typ	W2 typ	H typ	Packaging Unit (Pcs) 包装数量(Pcs)	Material 材质
245	129	43	195	120	40	23	20	APET



L typ	W typ	H typ	No. of Tray(Pcs) 托盘数量(Pcs)	Packaging Unit(Pcs) 包装数量(Pcs)	Material 材质
265	205	30	1	20	Paper



7.2 Packing(mm)  
包装(mm)



L typ	W typ	H typ	No. of Inner Carton 内盒数量(Pcs)	Packaging Unit( Pcs) 包装数量(Pcs)	Material 材料
275	232	261	8	160	Paper

7.3 Label Making  
标签标识

The following items will be marked on the tray of product label and shipping label.  
以下项目将明确标识于产品吸塑盘标签以及运输标签上。

<b>Production Label</b> 产品标签
■ Packing No. 包装流水号
■ Quantity 数量
■ Shipment Date 出货日期
■ Part No. 产品型号
■ Customer Part No. 客户型号
■ Customer Po No. 客户订单号

<b>Shipping Label</b> 运输标签
■ Packing No. 包装流水号
■ Quantity 数量
■ Shipment Date 出货日期
■ Part No. 产品型号
■ Customer Part No. 客户型号
■ Customer Po No. 客户订单号

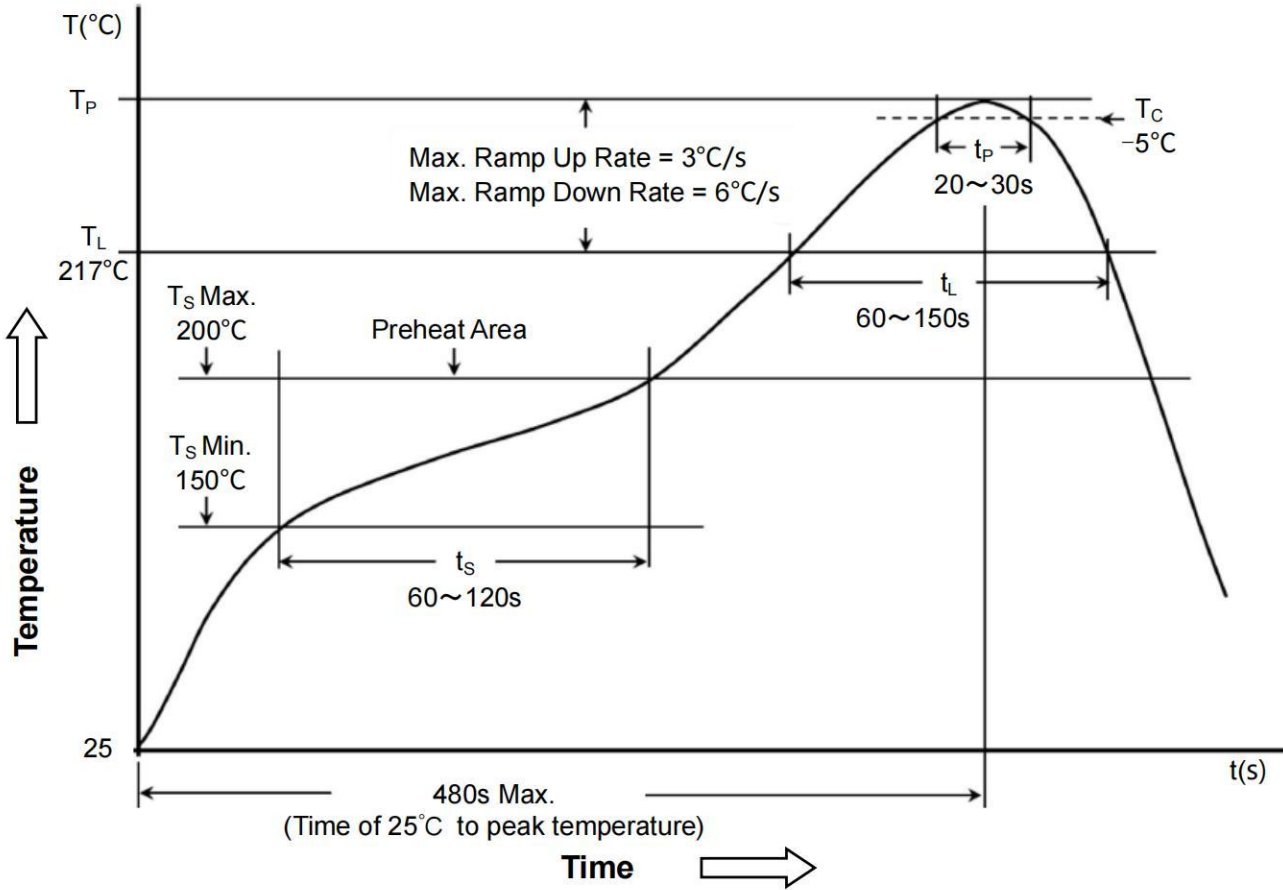


## 8 Soldering Specification

### 焊接规格

#### 8.1 Reflow Profile for SMT Components

SMT 回流焊温度曲线



#### 8.2 Classification of Peak Package Body Temperature (Tp)

封装体峰值温度(Tp)分类

	Package Thickness 封装厚度	Package Volume 封装体积		
		<350 mm <sup>3</sup>	350~2000 mm <sup>3</sup>	>2000 mm <sup>3</sup>
PB-Free Assembly 无铅装配	<1.6mm	260°C	260°C	260°C
	1.6~2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.  
回流焊参照标准 IPC/JEDEC J-STD-020D。